

Title (en)

METHOD FOR PRODUCING A PRINTED CIRCUIT BOARD PROVIDED WITH AT LEAST ONE COATING, AND COATING HEAD FOR CARRYING OUT THE METHOD

Title (de)

VERFAHREN ZUM HERSTELLEN EINER MIT MINDESTENS EINER LACKIERUNG VERSEHENEN LEITERPLATTE UND LACKIERKOPF ZUR DURCHFÜHRUNG DES VERFAHRENS

Title (fr)

PROCÉDÉ DE FABRICATION D'UNE CARTE DE CIRCUIT IMPRIMÉ POURVUE D'AU MOINS UNE COUCHE DE VERNIS, ET TÊTE DE VERNISSAGE POUR LA MISE EN UVRE DU PROCÉDÉ

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Application

**EP 18782366 A 20180927**

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Abstract (en)

[origin: WO2019081154A1] The invention discloses a method for producing a printed circuit board provided with at least one coating, the method comprising at least the following steps: mixing at least one first component with a second component of an at least two-component coating system to form a coating mixture by means of a dynamic mixer and/or by means of a static-dynamic mixer (120); feeding the coating mixture to a dispensing unit (140); and coating the printed circuit board by dispensing the coating mixture by means of the dispensing unit onto the printed circuit board. During the coating, the dispensing unit (140) is automatically moved relative to the printed circuit board in at least one dimension, in particular in two or three dimensions, and the mixer (120) is connected to the dispensing unit in such a way that the mixer is moved relative to the printed circuit board together with the dispensing unit (140). The invention further discloses to a coating head (100) for carrying out the method.

IPC 8 full level

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Citation (search report)

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